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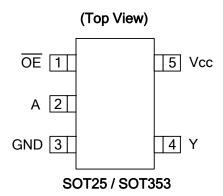




#### **Description**

The 74AHC1G125 is a single non-inverting buffer/bus driver with a 3-state output. The output enters a high impedance state when a HIGH-level is applied to the output enable  $(\overline{OE})$  pin. The device is designed for operation with a power supply range of 2.0V to 5.5V.

### **Pin Assignments**



#### **Features**

- Supply Voltage Range from 2.0V to 5.5V
- ± 8 mA Output Drive at 5.0V
- CMOS low power consumption
- Schmitt Trigger Action at All Inputs Make the Circuit Tolerant for Slower Input Rise and Fall Time.
- ESD Protection per JESD 22
  - o Exceeds 200-V Machine Model (A115-A)
  - o Exceeds 2000-V Human Body Model (A114-A)
  - Exceeds 1000-V Charged Device Model (C101C)
- Latch-Up Exceeds 100mA per JESD 78, Class II
- SOT25 and SOT353: Assembled with "Green" Molding Compound (no Br, Sb)
- Lead Free Finish / RoHS Compliant (Note 1)

### **Applications**

- General Purpose Logic
- Wide array of products such as:
  - o PCs, networking, notebooks, netbooks, PDAs
  - o Computer peripherals, hard drives, CD/DVD ROM
  - o TV, DVD, DVR, set top box
  - Phones, Personal Navigation / GPS
  - o MP3 players ,Cameras, Video Recorders

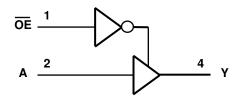
Notes: 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied. Please visit our website at http://www.diodes.com/products/lead\_free.html.



## **Pin Descriptions**

Pin Name	Pin No.	Description
ŌE	1	Output Enable
Α	2	Data Input
GND	3	Ground
Y	4	Data Output
Vcc	5	Supply Voltage

## **Logic Diagram**



## **Function Table**

Inp	Output	
ŌĒ	Α	Υ
L	Н	Н
L	L	L
Н	X	Z



## **Absolute Maximum Ratings (Note 2)**

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
V <sub>CC</sub>	Supply Voltage Range	-0.5 to 6.5	V
VI	Input Voltage Range	-0.5 to 6.5	V
V <sub>O</sub>	Voltage applied to output in high or low state	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> <0	-20	mA
lok	Output Clamp Current (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20	mA
Io	Continuous output current (V <sub>O</sub> = 0 to V <sub>CC</sub> )	±25	mA
Icc	Continuous current through V <sub>CC</sub>	50	mA
I <sub>GND</sub>	Continuous current through GND	-50	mA
TJ	Operating Junction Temperature	-40 to 150	°C
T <sub>STG</sub>	Storage Temperature	-65 to 150	°C

Notes: 2. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

## **Recommended Operating Conditions (Note 3)**

Symbol		Parameter	Min	Max	Unit	
$V_{CC}$	Operating Voltage		2	5.5	V	
		$V_{CC} = 2V$	1.5			
$V_{IH}$	High-level Input Voltage	$V_{CC} = 3V$	2.1		V	
		$V_{CC} = 5.5V$	3.85			
		$V_{CC} = 2V$		0.5		
$V_{IL}$	Low-level input voltage	$V_{CC} = 3V$		0.9	V	
		$V_{CC} = 5.5V$		1.65		
VI	Input Voltage		0	5.5	V	
Vo	Output Voltage		0	$V_{CC}$	V	
		$V_{CC} = 2V$		-50	uA	
I <sub>OH</sub>	High-level output current	$V_{CC} = 3.3V \pm 0.3V$		-4	m A	
		$V_{CC} = 5V \pm 0.5V$		-8	mA	
		$V_{CC} = 2V$		50	uA	
I <sub>OL</sub>	Low-level output current	$V_{CC} = 5V \pm 0.5V$		4	m A	
		$V_{CC} = 3V$		8	mA	
Δt/ΔV	Input transition rise or fall	$V_{CC} = 3.3V \pm 0.3V$		100	20/1/	
Δι/Δν	rate	$V_{CC} = 5V \pm 0.5V$		20	ns/V	
T <sub>A</sub>	Operating free-air temperature		-40	125	ōС	

Notes: 3. Unused inputs should be held at  $V_{CC}$  or Ground.



## **Electrical Characteristics**

0		T I O I''.	V		25ºC		-40ºC t	o 85ºC	-40ºC to	o 125ºC	
Symbol	Parameter	Test Conditions	V <sub>CC</sub>	Min	Тур.	Max	Min	Max	Min	Max	Unit
			2V	1.9	2		1.9		1.9		
		$I_{OH} = -50\mu A$	3V	2.9	3		2.9		2.9		
V <sub>OH</sub>	High Level		4.5V	4.4	4.5		4.4		4.4		V
	Output Voltage	$I_{OH} = -4mA$	3V	2.58			2.48		2.40		
		$I_{OH} = -8mA$	4.5V	3.94			3.8		3.70		
			2V			0.1		0.1		0.1	
		$I_{OL} = 50\mu A$	3V			0.1		0.1		0.1	
V <sub>OL</sub>	Low Level		4.5V			0.1		0.1		0.1	V
	Output Voltage	$I_{OL} = 4mA$	3V			0.36		0.44		0.55	
		$I_{OL} = 8mA$	4.5V			0.36		0.44		0.55	
II	Input Current	$V_I = 5.5V$ or GND	0 to 5.5V			± 0.1		± 1		± 2	μΑ
I <sub>OZ</sub>	Z State Leakage Current	V <sub>O</sub> =0 to 5.5V	5.5V			0.25		2.5		10	μΑ
I <sub>CC</sub>	Supply Current	$V_I = 5.5V$ or GND $I_{O}=0$	5.5V			1		10		40	μΑ
C <sub>i</sub>	Input Capacitance	$V_I = V_{CC} - or$ GND	5.5V		2.0	10		10		10	pF
	Thermal Resistance	SOT25	(Note 4)		195						°C/W
θ <sub>JA</sub>	Junction-to- Ambient SOT353	(Note 4)		430						C/W	
Δ	Thermal Resistance	SOT25	(Note 4)		58						°C/\\
θ <sub>JC</sub>	Junction-to- Case	SOT353	(Note 4)		155						°C/W

Note: 4. Test conditions for SOT25, and SOT353: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



# **Switching Characteristics**

**V<sub>CC</sub> = 3.3V ± 0.3** (see Figure 1)

Parameter	From	TO			25ºC		-40ºC t	o 85ºC	-40ºC to	o 125ºC	Unit
Parameter	(Input)	(OUTPUT)		Min	Тур.	Max	Min	Max	Min	Max	Ullit
	^	<b>&gt;</b>	C <sub>L</sub> =15pF	0.6	4.7	8.0	0.6	9.5	0.6	11.5	ns
t <sub>pd</sub>	Α	Ť	C <sub>L</sub> =50pF	0.6	6.6	11.5	0.6	13.0	0.6	14.5	ns
		<b>V</b>	C <sub>L</sub> =15pF	0.6	5.0	8.0	0.6	9.5	0.6	10.5	ns
t <sub>en</sub>	OE	Ť	C <sub>L</sub> =50pF	0.6	6.9	11.5	0.6	13.0	0.6	14.5	ns
4		<b>V</b>	C <sub>L</sub> =15pF	0.6	6.0	9.7	0.6	11.5	0.6	12.5	ns
t <sub>dis</sub>	OE	Ť	C <sub>L</sub> =50pF	0.6	8.3	13.2	0.6	15.0	0.6	16.5	ns

#### $V_{CC} = 5V \pm 0.5V$ (see Figure 1)

Davamatav	From	то			25ºC		-40ºC t	o 85ºC	-40ºC to	o 125ºC	I I mit
Parameter	(Input)	(OUTPUT)		Min	Тур.	Max	Min	Max	Min	Max	Unit
	^	V	C <sub>L</sub> =15pF	0.6	3.4	5.5	0.6	6.5	0.6	7.0	ns
t <sub>pd</sub>	Α	Y	C <sub>L</sub> =50pF	0.6	4.8	7.5	0.6	8.5	0.6	9.5	ns
	<u> </u>	V	C <sub>L</sub> =15pF	0.6	3.6	5.1	0.6	6.0	0.6	6.5	ns
t <sub>en</sub>	OE	Y	C <sub>L</sub> =50pF	0.6	6.5	11.4	0.6	13.0	0.6	14.5	ns
+		V	C <sub>L</sub> =15pF	0.6	4.1	6.8	0.6	8.0	0.6	8.5	ns
t <sub>dis</sub>	OE	ľ	C <sub>L</sub> =50pF	0.6	5.7	8.8	0.6	10.0	0.6	11.0	ns

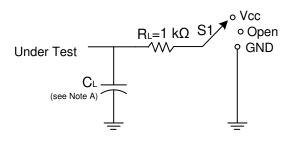
## **Operating Characteristics**

 $T_A = 25 \, {}^{\circ}C$ 

	Parameter	Test Conditions	V <sub>CC</sub> = 5 V Typ.	Unit
$C_{\sf pd}$	Power dissipation capacitance	f = 1 MHz No Load	12	pF



#### **Parameter Measurement Information**

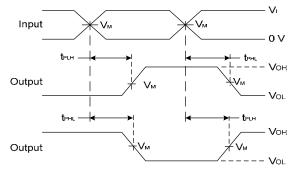


TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	Vload
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

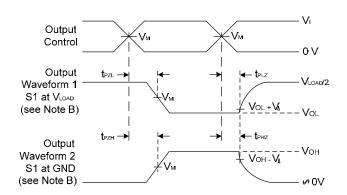
V	In	puts	V	0	V.
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	CL	<b>V</b> Δ
3.3V±0.3V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	15pF	0.3V
5V±0.5V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	15pF	0.3V
3.3V±0.3V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	50pF	0.3V
5V±0.5V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	50pF	0.3V



**Voltage Waveform Pulse Duration** 



**Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs** 



**Voltage Waveform Enable and Disable Times** Low and High Level Enabling

Figure 1. Load Circuit and Voltage Waveforms

Notes: A. Includes test lead and test apparatus capacitance.

B. All pulses are supplied at pulse repetition rate ≤ 1 MHz.

C. Inputs are measured separately one transition per measurement.

D. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis.</sub>

E. tPZL and tPZH are the same as tEN.

F. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>PD</sub>.



## **Ordering Information**

T4 AHC1G 125 XX - 7

Logic Device Function Package Packing

74 : Logic Prefix 125 : 3-State Buffer W5 : SOT25 7 : Tape & Reel

**SE: SOT353** 

AHC: 2 to 5.5V Family 1G: One gate

	Davies	Package	Packaging	7" Tape and Reel	
	Device	Code	(Note 5)	Quantity	Part Number Suffix
<b>PD</b> ,	74AHC1G125W5-7	W5	SOT25	3000/Tape & Reel	-7
<b>Pb</b> ,	74AHC1G125SE-7	SE	SOT353	3000/Tape & Reel	-7

OE-Low

Notes: 5. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

## **Marking Information**

#### (Top View)

 $\begin{array}{c|c} \hline 5 & \hline & 4 \\ \hline & \underline{XX} : Identification code \\ \underline{Y} : Year 0^9 \end{array}$ 

<u>XX Y W X</u>

<u>W</u>: Week: A~Z: 1~26 week; a~z: 27~52 week; z represents 52 and 53 week

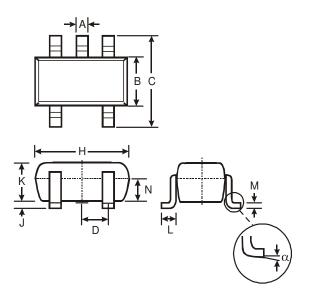
2 3 <u>X</u>: A~Z: Internal code

Part Number	Package	Identification Code
74AHC1G125W5	SOT25	YY
74AHC1G125SE	SOT353	YY



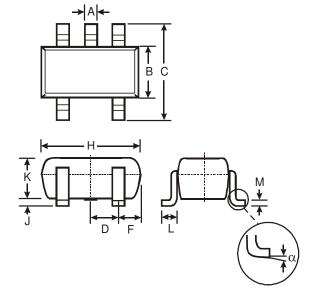
## Package Outline Dimensions (All Dimensions in mm)

## (1) Package Type: SOT25



SOT25				
Dim	Min	Max	Тур	
Α	0.35	0.50	0.38	
В	1.50	1.70	1.60	
C	2.70	3.00	2.80	
D	_		0.95	
Н	2.90	3.10	3.00	
7	0.013	0.10	0.05	
K	1.00	1.30	1.10	
L	0.35	0.55	0.40	
M	0.10	0.20	0.15	
N	0.70	0.80	0.75	
α	0°	8°		
All Dimensions in mm				

### (2) Package Type: SOT353



SOT353				
Dim	Min	Max		
Α	0.10	0.30		
В	1.15	1.35		
С	2.00	2.20		
D	0.65 Typ			
F	0.40	0.45		
Н	1.80	2.20		
J	0	0.10		
K	0.90	1.00		
L	0.25	0.40		
М	0.10	0.22		
α	0°	8°		
All Dimensions in mm				



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